



DO214AA (SMB) Rectifier

Material Content Declaration					
Material name	Substance name e.g. Copper (Cu), Gold (Au)	CAS no., if known	Substance mass (mg)	% OF Weight (%)	ppm Of Total Weight
Lead Frame 31.19%	Copper (Cu)	7440-50-8	32.4335	99.9787	311,859.5
	Phosphorus (P)	7723-14-0	0.0003	0.0010	3.1
	Arsenic (As)	7440-38-2	0.0003	0.0010	3.1
	Tin (Sn)	7440-31-5	0.0003	0.0010	3.1
	Oxygen (O)	7782-44-7	0.0002	0.0005	1.6
	Sulfur (S)	7704-34-9	0.0039	0.0120	37.4
	Iron (Fe)	7439-89-6	0.0002	0.0007	2.1
	Nickel (Ni)	7440-02-0	0.0001	0.0003	0.9
	Bismuth (Bi)	7440-69-9	0.0006	0.0020	6.2
	Antimony (Sb)	1309-64-4	0.0006	0.0020	6.2
	Lead (Pb)	7439-92-1	0.0002	0.0005	1.6
	Zinc (Zn)	7440-66-6	0.0001	0.0003	0.9
	Total		32.44		
Solder Wafer 0.98%	Lead (Pb)	7439-92-1	0.94	92.50	9,072.1
	Tin (Sn)	7440-31-5	0.05	5.00	490.4
	Silver (Ag)	7440-22-4	0.03	2.50	245.2
	Total		1.02		
Chip 1.30%	Silicon (Si)	7440-21-3	1.288	95.40	12,383.6
	Lead (Pb)	7439-92-1	0.062	4.60	597.1
	Total		1.35		
Molding 65.86%	Silica (SiO ₂)	7631-86-9	50.77	74.11	488,171.2
	Epoxy resin	29690-82-2	11.65	17.00	112,018.8
	Phenolic resin	9003-35-4	6.03	8.80	57,980.5
	Phosphorus(P)	7723-14-0	0.03	0.05	288.5
	Carbon Black	1333-86-4	0.03	0.04	288.5
	Total		68.50		
Plating 0.67%	Tin (Sn)	7440-31-5	0.69	100.00	6,634.6
	Total		0.69		
	Total mass		104.00		



